



SamHop Microelectronics Corp.

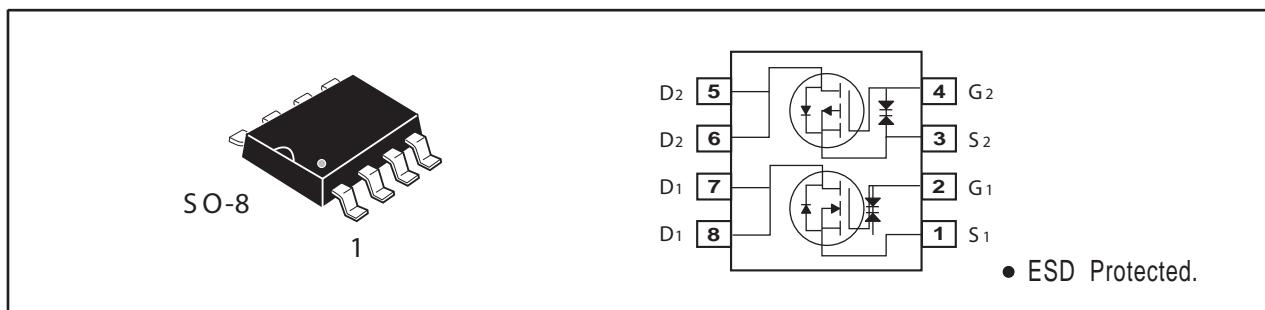
**STM8324**

Ver 1.2

Dual Enhancement Mode Field Effect Transistor (N and P Channel)

PRODUCT SUMMARY (N-Channel)		
VDSS	ID	RDS(ON) (mΩ) Max
30V	6.5A	31 @ VGS=10V
		42 @ VGS=4.5V

PRODUCT SUMMARY (P-Channel)		
VDSS	ID	RDS(ON) (mΩ) Max
-30V	-6A	35 @ VGS=-10V
		53 @ VGS=-4.5V



ABSOLUTE MAXIMUM RATINGS ($T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	N-Channel	P-Channel	Units
V_{DS}	Drain-Source Voltage	30	-30	V
V_{GS}	Gate-Source Voltage	± 20	± 20	V
I_D	Drain Current-Continuous ^a	$T_A=25^\circ\text{C}$	6.5	A
		$T_A=70^\circ\text{C}$	5.2	A
I_{DM}	-Pulsed ^b	24	-22	A
E_{AS}	Single Pulse Avalanche Energy ^d	12	64	mJ
P_D	Maximum Power Dissipation ^a	$T_A=25^\circ\text{C}$	2	W
		$T_A=70^\circ\text{C}$	1.28	
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 to 150		°C

THERMAL CHARACTERISTICS

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient ^a	62.5	°C/W
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Details are subject to change without notice.

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N-Channel ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =24V , V _{GS} =0V			1	uA
I _{GSS}	Gate-Body Leakage Current	V _{GS} = ±20V , V _{DS} =0V			±10	uA
ON CHARACTERISTICS						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	1	1.9	3	V
R _{D(S(ON))}	Drain-Source On-State Resistance	V _{GS} =10V , I _D =6.5A		24	31	m ohm
		V _{GS} =4.5V , I _D =5.6A		33	42	m ohm
g _{FS}	Forward Transconductance	V _{DS} =5V , I _D =6.5A		15		S
DYNAMIC CHARACTERISTICS ^c						
C _{ISS}	Input Capacitance	V _{DS} =15V, V _{GS} =0V f=1.0MHz		478		pF
C _{OSS}	Output Capacitance			100		pF
C _{rss}	Reverse Transfer Capacitance			65		pF
SWITCHING CHARACTERISTICS ^c						
t _{D(ON)}	Turn-On Delay Time	V _{DD} =15V I _D =1A V _{GS} =10V R _{GEN} =6 ohm		10.5		ns
t _r	Rise Time			10		ns
t _{D(OFF)}	Turn-Off Delay Time			17		ns
t _f	Fall Time			20		ns
Q _g	Total Gate Charge	V _{DS} =15V, I _D =6.5A, V _{GS} =10V		8.1		nC
		V _{DS} =15V, I _D =6.5A, V _{GS} =4.5V		4		nC
Q _{gs}	Gate-Source Charge	V _{DS} =15V, I _D =6.5A, V _{GS} =10V		1.3		nC
Q _{gd}	Gate-Drain Charge			2.2		nC
DRAIN-SOURCE DIODE CHARACTERISTICS						
I _s	Maximum Continuous Drain-Source Diode Forward Current			1.7		A
V _{SD}	Diode Forward Voltage ^b	V _{GS} =0V, I _s =1.7A		0.79	1.2	V

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P-Channel ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu\text{A}$	-30			V
Idss	Zero Gate Voltage Drain Current	$V_{DS}=-24V, V_{GS}=0V$			-1	μA
IGSS	Gate-Body Leakage Current	$V_{GS} = \pm 20V, V_{DS}=0V$			± 10	μA
ON CHARACTERISTICS						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu\text{A}$	-1.0	-1.8	-3.0	V
RDS(ON)	Drain-Source On-State Resistance	$V_{GS}=-10V, I_D=-6A$		27	35	m ohm
		$V_{GS}=-4.5V, I_D=-4.9A$		40	53	m ohm
gFS	Forward Transconductance	$V_{DS}=-5V, I_D=-6A$		8.5		S
DYNAMIC CHARACTERISTICS ^c						
Ciss	Input Capacitance	$V_{DS}=-15V, V_{GS}=0V$ $f=1.0\text{MHz}$		790		pF
Coss	Output Capacitance			215		pF
CRSS	Reverse Transfer Capacitance			120		pF
SWITCHING CHARACTERISTICS ^c						
tD(ON)	Turn-On Delay Time	$V_{DD}=-15V$ $I_D=-1A$ $V_{GS}=-10V$ $R_{GEN}=6\text{ ohm}$		10		ns
tr	Rise Time			15		ns
tD(OFF)	Turn-Off Delay Time			67		ns
tf	Fall Time			33		ns
Qg	Total Gate Charge	$V_{DS}=-15V, I_D=-6A, V_{GS}=-10V$		15		nC
		$V_{DS}=-15V, I_D=-6A, V_{GS}=-4.5V$		7.5		nC
Qgs	Gate-Source Charge	$V_{DS}=-15V, I_D=-6A,$ $V_{GS}=-10V$		1.4		nC
Qgd	Gate-Drain Charge			4		nC
DRAIN-SOURCE DIODE CHARACTERISTICS						
Is	Maximum Continuous Drain-Source Diode Forward Current			-1.7		A
VSD	Diode Forward Voltage ^b	$V_{GS}=0V, I_S=-1.7A$		-0.76	-1.2	V
Notes						
a.Surface Mounted on FR4 Board,t < 10sec.						
b.Pulse Test:Pulse Width < 300us, Duty Cycle < 2%.						
c.Guaranteed by design, not subject to production testing.						
d.Starting $T_J=25^\circ\text{C}$, $V_{DD} = 20V$, $V_{GS}=10V$, $L=0.5\text{mH}$.(See Figure13)						

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N-Channel

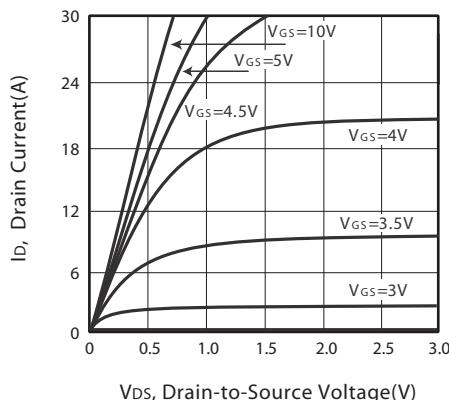


Figure 1. Output Characteristics

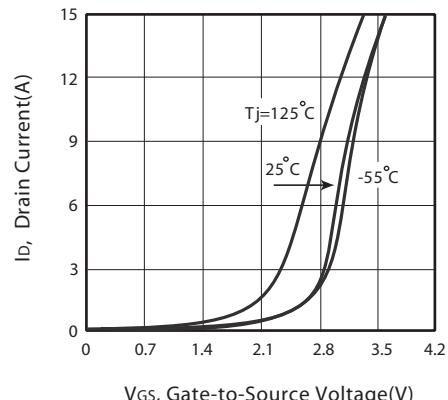


Figure 2. Transfer Characteristics

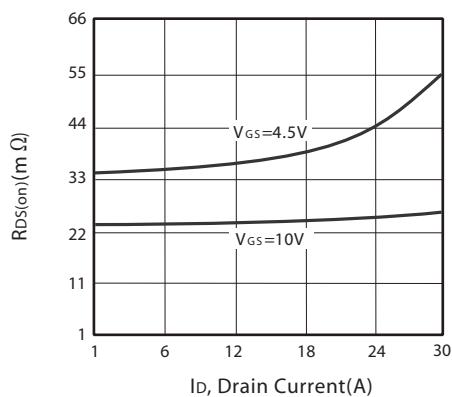


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

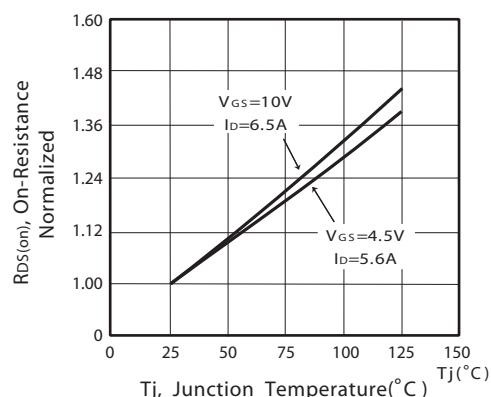


Figure 4. On-Resistance Variation with Drain Current and Temperature

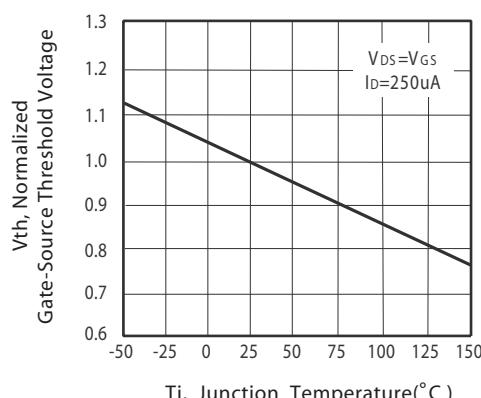


Figure 5. Gate Threshold Variation with Temperature

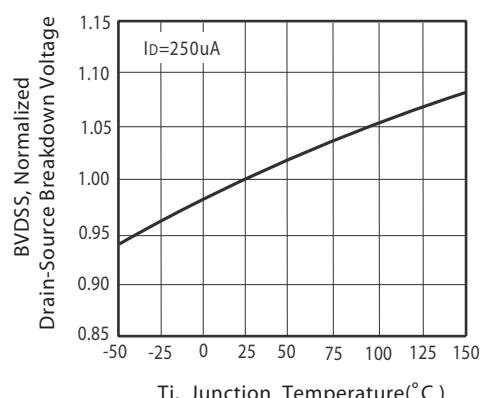
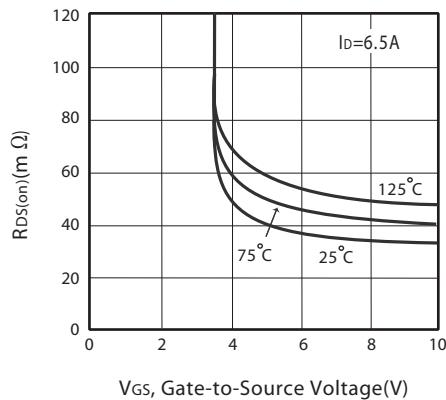


Figure 6. Breakdown Voltage Variation with Temperature

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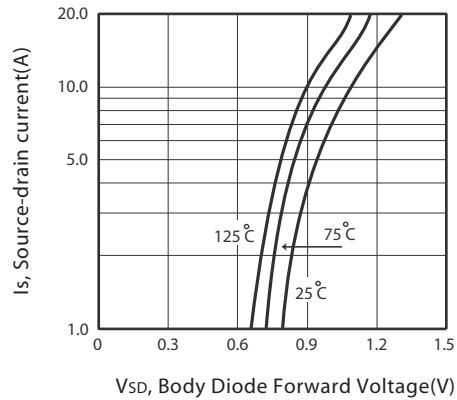
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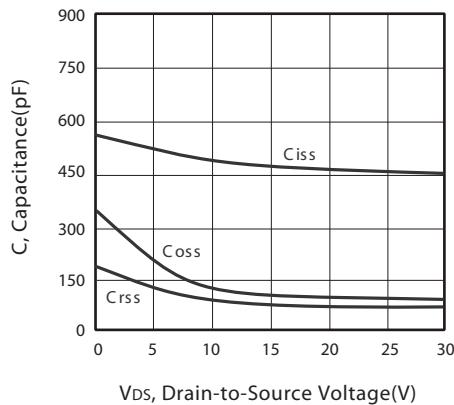
V_{GS}, Gate-to-Source Voltage(V)

Figure 7. On-Resistance vs. Gate-Source Voltage



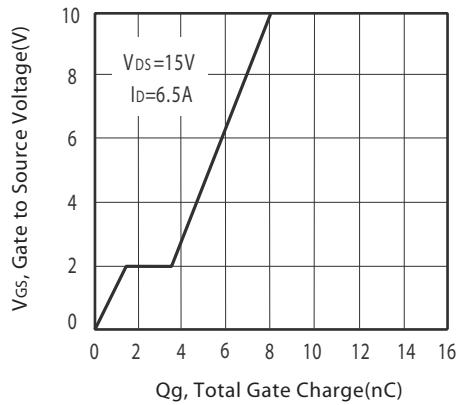
V_{SD}, Body Diode Forward Voltage(V)

Figure 8. Body Diode Forward Voltage Variation with Source Current



V_{DS}, Drain-to-Source Voltage(V)

Figure 9. Capacitance



Q_g, Total Gate Charge(nC)

Figure 10. Gate Charge

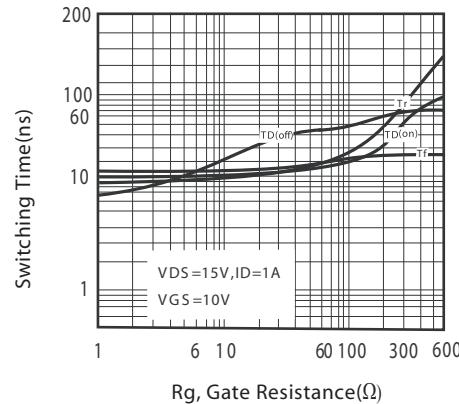


Figure 11. switching characteristics

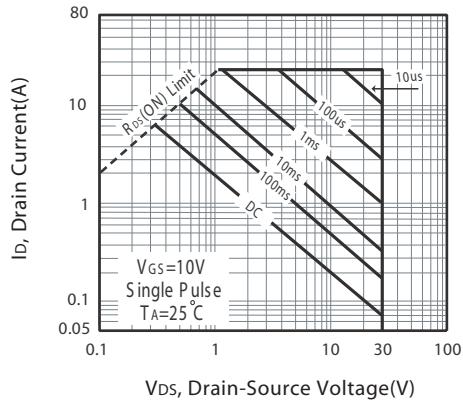
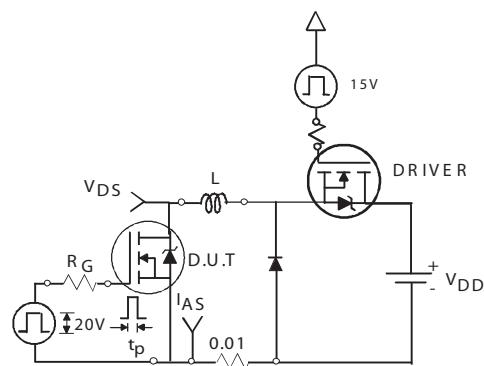


Figure 12. Maximum Safe Operating Area

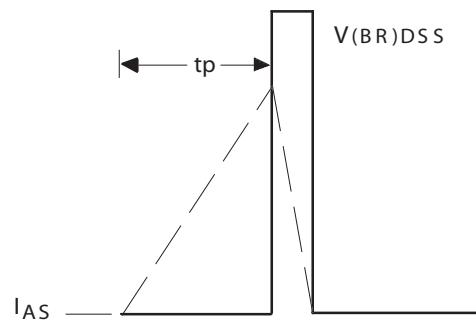
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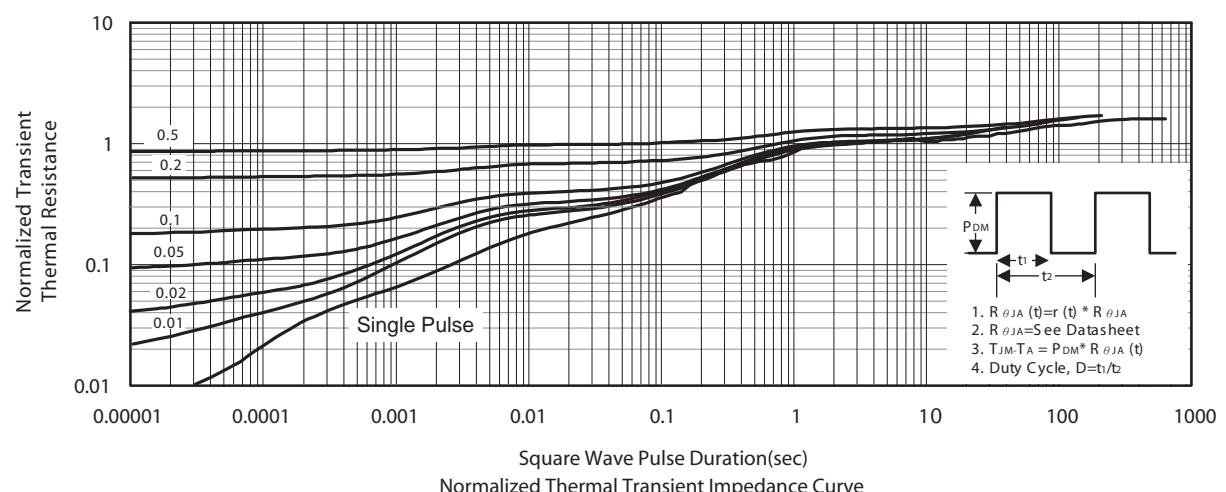
Unclamped Inductive Test Circuit

Figure 13a.



Unclamped Inductive Waveforms

Figure 13b.



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P-Channel

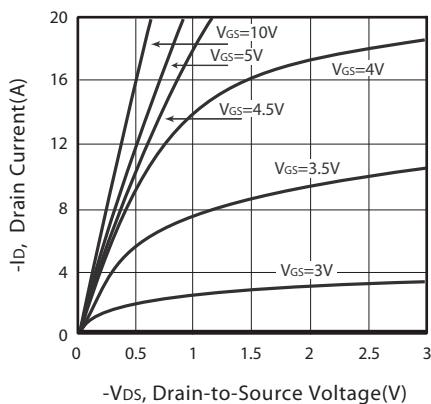


Figure 1. Output Characteristics

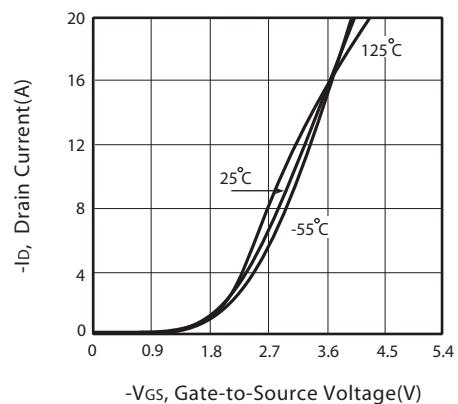


Figure 2. Transfer Characteristics

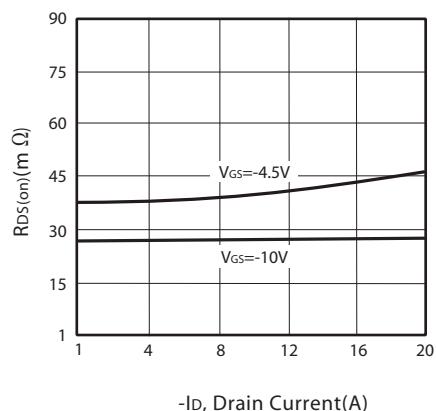


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

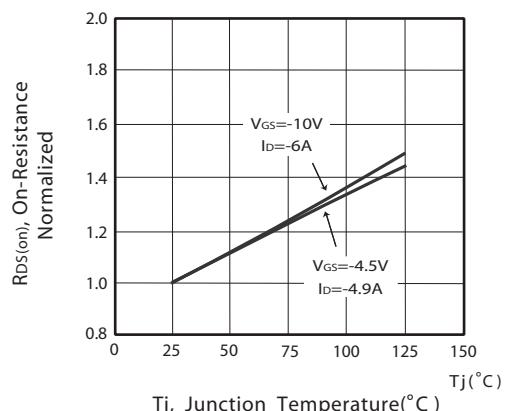


Figure 4. On-Resistance Variation with Drain Current and Temperature

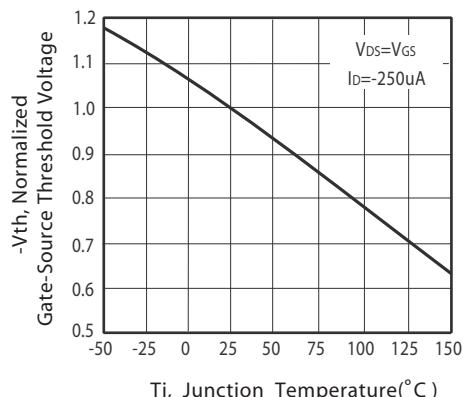


Figure 5. Gate Threshold Variation with Temperature

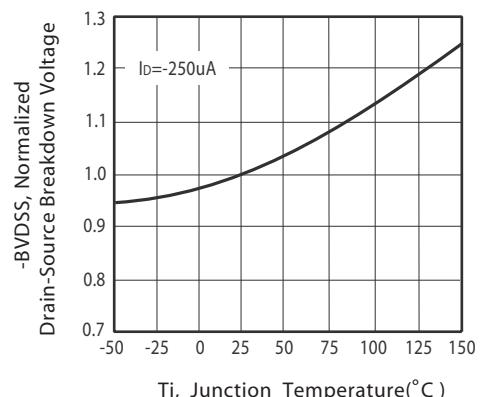


Figure 6. Breakdown Voltage Variation with Temperature

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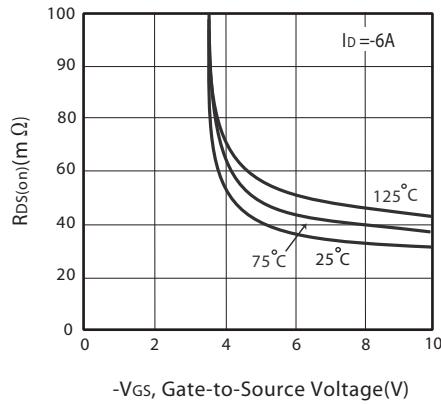


Figure 7. On-Resistance vs. Gate-Source Voltage

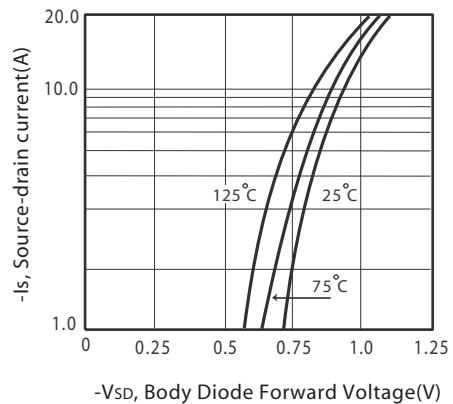


Figure 8. Body Diode Forward Voltage Variation with Source Current

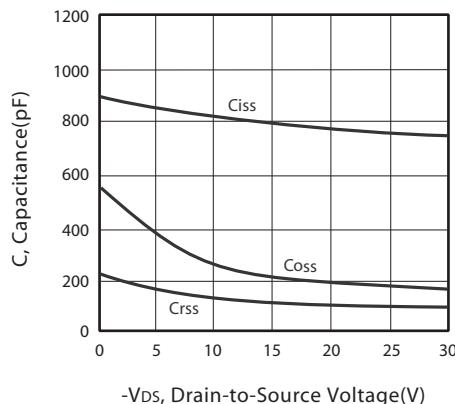


Figure 9. Capacitance

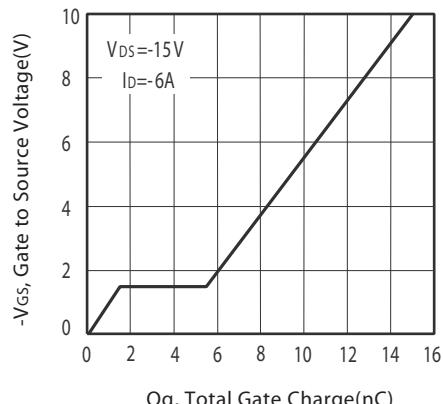


Figure 10. Gate Charge

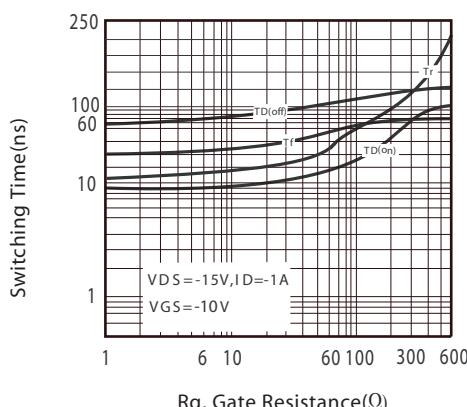


Figure 11. switching characteristics

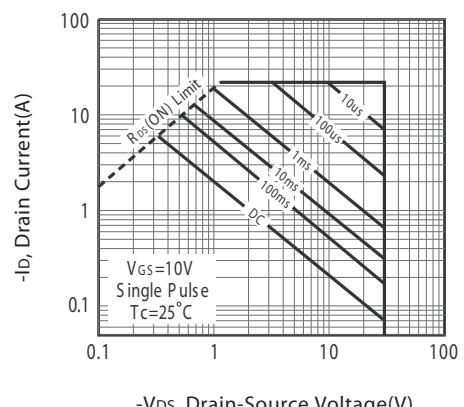
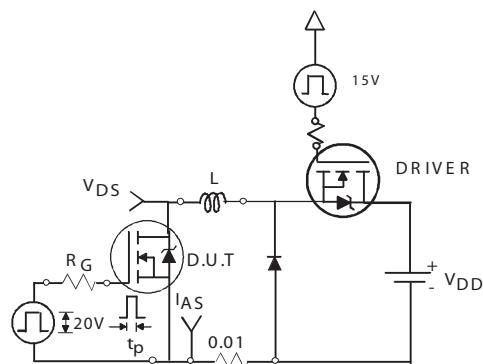


Figure 12. Maximum Safe Operating Area

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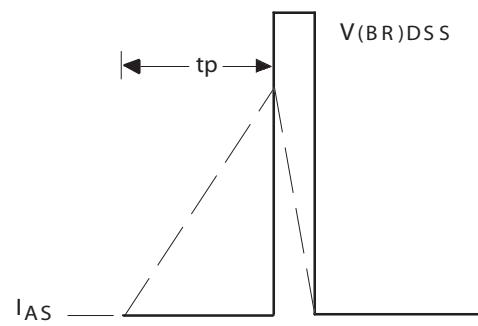
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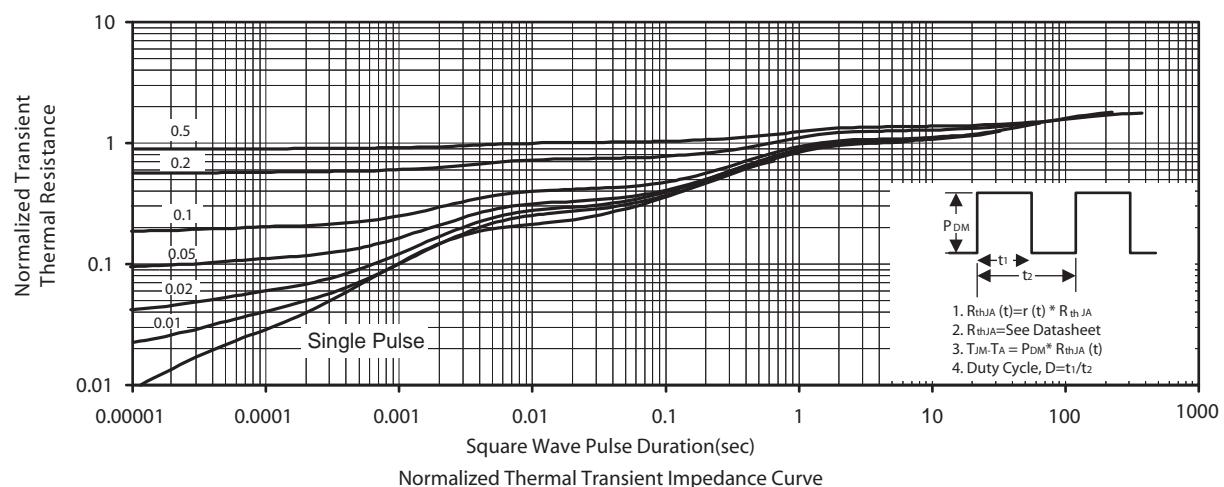
Unclamped Inductive Test Circuit

Figure 13a.



Unclamped Inductive Waveforms

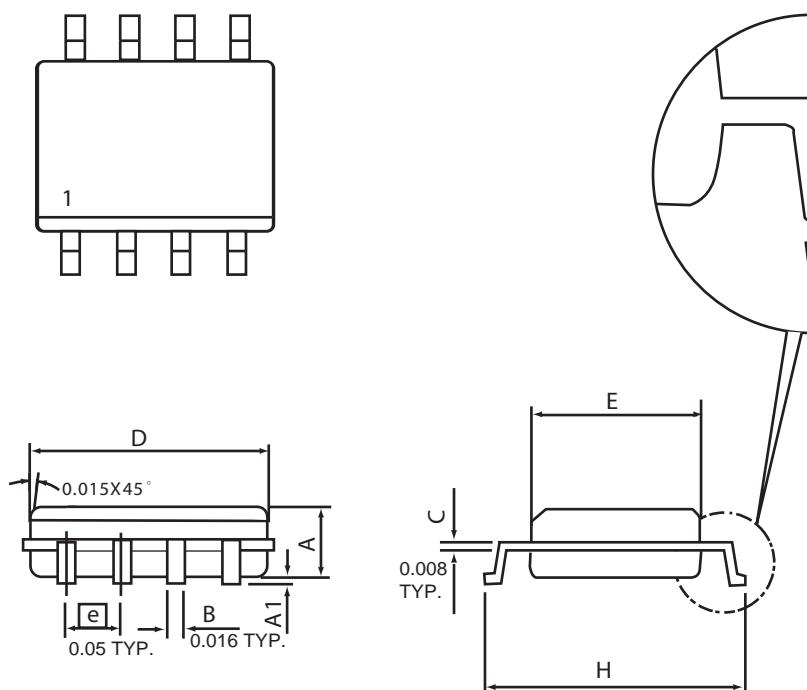
Figure 13b.



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PACKAGE OUTLINE DIMENSIONS

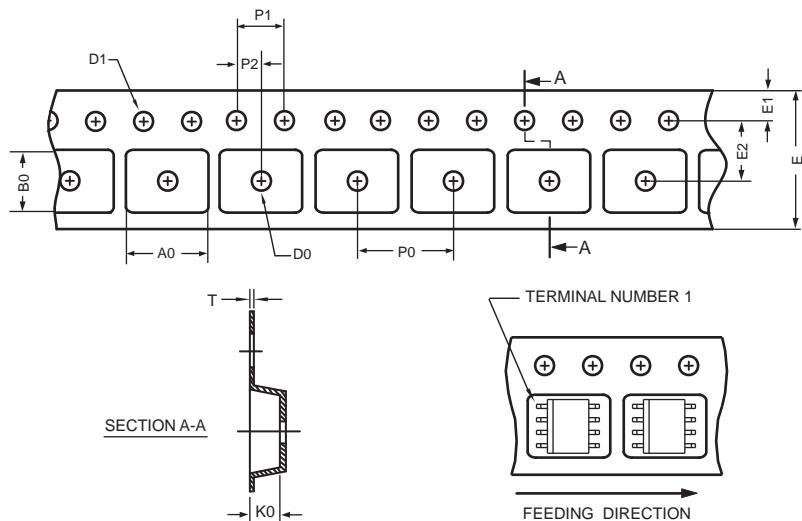
SO-8



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.053	0.069
A1	0.10	0.25	0.004	0.010
D	4.80	4.98	0.189	0.196
E	3.81	3.99	0.150	0.157
H	5.79	6.20	0.228	0.244
L	0.41	1.27	0.016	0.050
θ	0 °	8 °	0 °	8 °

SO-8 Tape and Reel Data

SO-8 Carrier Tape



unit:mm

PACKAGE	A0	B0	K0	D0	D1	E	E1	E2	P0	P1	P2	T
SOP 8N 150mil	6.50 ±0.15	5.25 ±0.10	2.10 ±0.10	ø 1.5 (MIN)	ø 1.55 ±0.10	12.0 +0.3 -0.1	1.75 ±0.10	5.5 ±0.10	8.0 ±0.10	4.0 ±0.10	2.0 ±0.10	0.30 ±0.013

SO-8 Reel

